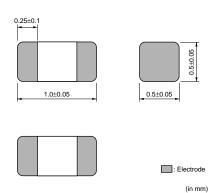
Data Sheet

EMIFIL[®] (Inductor type) Chip Ferrite Bead BLM15AX_SN Series (0402 Size)

Dimensions



Equivalent Circuit

1

(Resistance element becomes dominant at high frequencies.)

Packaging

Code	Packaging	Minimum Quantity
D	180mm Paper Tape	10000
J	330mm Paper Tape	50000
В	Bulk(Bag)	1000

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance (max.)	Operating Temperature Range
BLM15AX100SN1	10ohm(Typ.)	-	1740mA	0.02ohm	-55 to +125°C
BLM15AX700SN1	70ohm±25%	-	780mA	0.1ohm	-55 to +125°C
BLM15AX121SN1	120ohm±25%	-	680mA	0.13ohm	-55 to +125°C
BLM15AX221SN1	220ohm±25%	-	580mA	0.18ohm	-55 to +125°C
BLM15AX601SN1	600ohm±25%	-	420mA	0.34ohm	-55 to +125°C
BLM15AX102SN1	1000ohm±25%	-	350mA	0.49ohm	-55 to +125°C

Number of Circuits: 1

Continued on the following page.

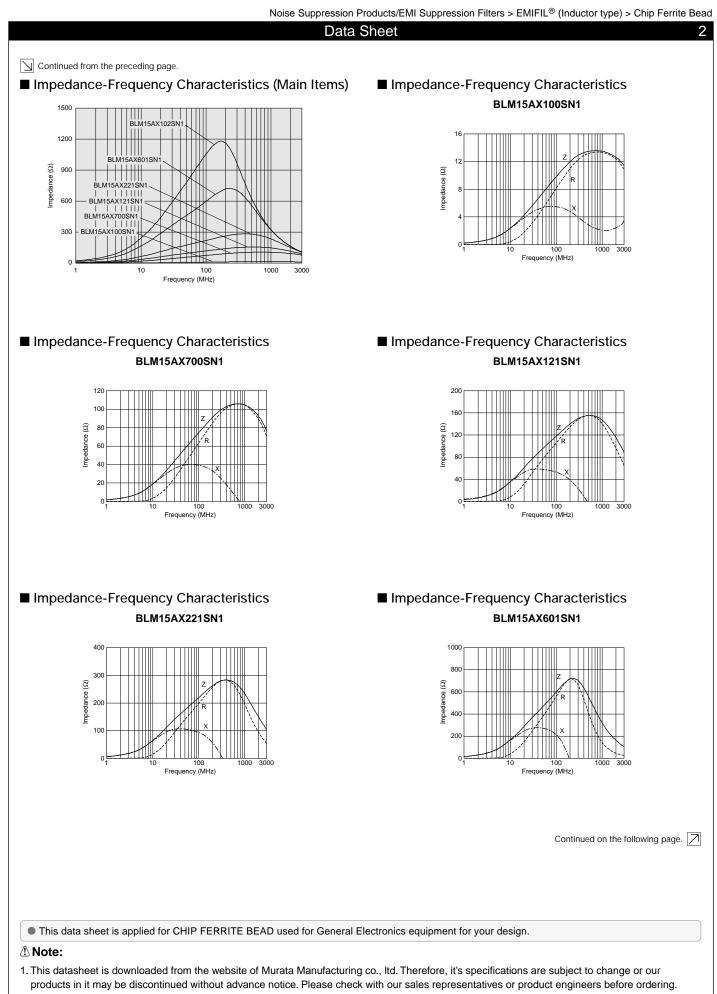
• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

A Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.

2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

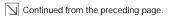


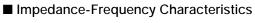


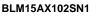
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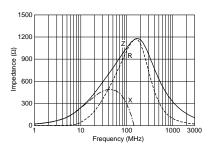












■ ①Caution/Notice

ACaution (Rating)

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Data Sheet

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

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